

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t6654bis6-4.096#trmpbf

(Engineering Calculation)

TSOT-23

(printed on: 2020-07-11 20:41:50)

**TOTAL MASS (g) : 0.012543**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
<b>Active Device</b>	Linear Technology	Silicon (Si)	7440-21-3	0.000567	1000000	45205.3789062		
<b>Die Coat</b>	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
<b>Lead Frame</b>	A42	Copper (Cu)	7440-50-8	0.000000	0	0		
		Iron (Fe)	7439-89-6	0.002726	580000	217336.609375		
		Phosphorus (P)	7723-14-0	0.000000	0	0		
		Zinc (Zn)	7440-66-6	0.000000	0	0		
		Nickel (Ni)	7440-02-0	0.001974	420000	157381.671875		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.004700</b>	<b>1000000</b>	<b>374718.28125</b>		
<b>Plating</b>	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000644	1000000	51324.921875		
		<b>External Plating Total:</b>				<b>0.000644</b>	<b>1000000</b>	<b>51324.921875</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000080	1000000	6378.18310547		
		<b>Internal Plating Total:</b>				<b>0.000080</b>	<b>1000000</b>	<b>6378.18310547</b>
<b>Die Attach</b>	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000409	750000	32608.4648438		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000136	250000	10842.9121094		
<b>Die Attach Total:</b>				<b>0.000545</b>	<b>1000000</b>	<b>43451.375</b>		
<b>Encapsulation</b>	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.000772	130000	61549.46875		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.004930	830000	393055.53125		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000208	35000	16583.2773438		
		Carbon Black (C)	1333-86-4	0.000030	5000	2391.81860352		
		<b>Encapsulation Total:</b>				<b>0.005940</b>	<b>1000000</b>	<b>473580.125</b>
<b>Bond Wire Estimated</b>	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000067	1000000	5341.72851562		
					<b>TOTAL MASS (g) :</b>	<b>0.012543</b>		